

ABSTRACT

A semiconductor device comprising: a semiconductor chip (10) on which a plurality of electrodes are formed; a first flexible substrate (20) which is larger than the surface of the semiconductor chip (10) on which the electrodes (12) are formed, having a wiring pattern (22) formed thereon, and having the semiconductor chip (10) mounted thereon; a plurality of external terminals (38) electrically connected to the electrodes (12) by the wiring pattern (22); and a second flexible substrate (30) adhered to the first flexible substrate (20) avoiding the semiconductor chip (10).

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